

Silicon Epitaxial Schottky Barrier Type

1SS374

FEATURES

- Low forward voltage: $V_{F(2)}=0.23V(\text{typ})$.
- Small Package

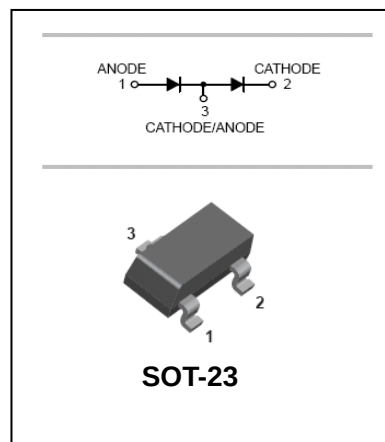


Lead-free

APPLICATIONS

- High Speed Switching Applications.

ORDERING INFORMATION



Type No.	Marking	Package Code
1SS374	N9	SOT-23

MAXIMUM RATING @ $T_a=25^{\circ}\text{C}$ unless otherwise specified

Parameter	Symbol	Limits	Unit
Maximum (peak) reverse voltage	V_{RM}	15	V
DC Reverse Voltage	V_R	10	V
Average rectified output current	I_O	100	mA
Forward Surge Current @ $t=10\text{ms}$	I_{FSM}	200	mA
Power Dissipation	P_d	150	mW
Junction temperature	T_j	125	$^{\circ}\text{C}$
Storage temperature range	T_{stg}	-55 to +125	$^{\circ}\text{C}$

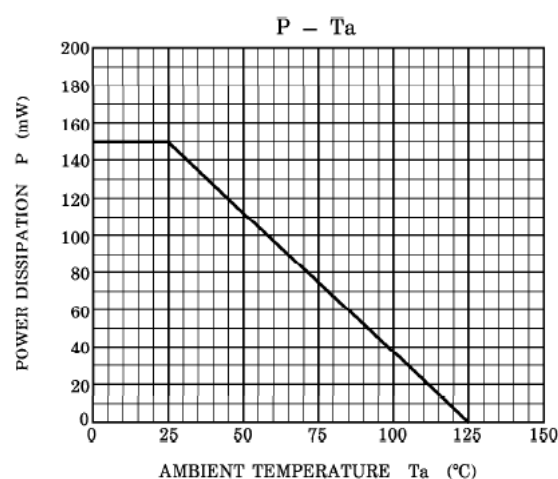
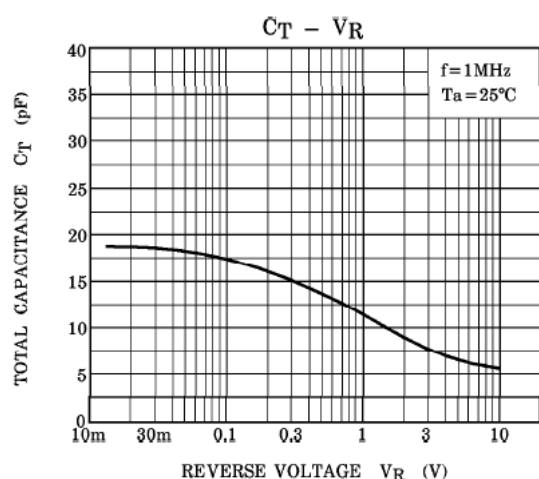
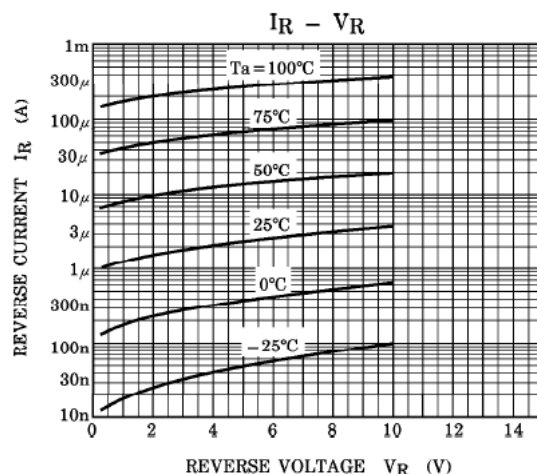
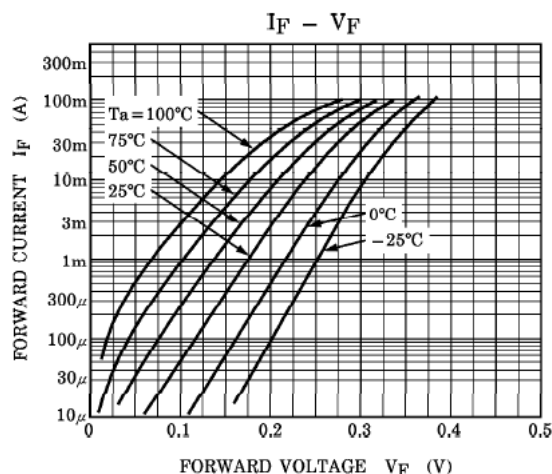
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ELECTRICAL CHARACTERISTICS @ $T_a=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Test conditions	MIN	Typ	MAX	UNIT
Reverse voltage leakage current	I_R	$V_R=10\text{V}$	-	-	20	μA
Forward voltage	V_F	$I_F=1\text{mA}$	-	0.18	-	V
		$I_F=5\text{mA}$	-	0.23	0.32	
		$I_F=100\text{mA}$	-	0.35	0.50	
Diode capacitance	C_T	$V_R=0\text{V}, f=1\text{MHz}$	-	20	40	pF

TYPICAL CHARACTERISTICS @ $T_a=25^\circ\text{C}$ unless otherwise specified



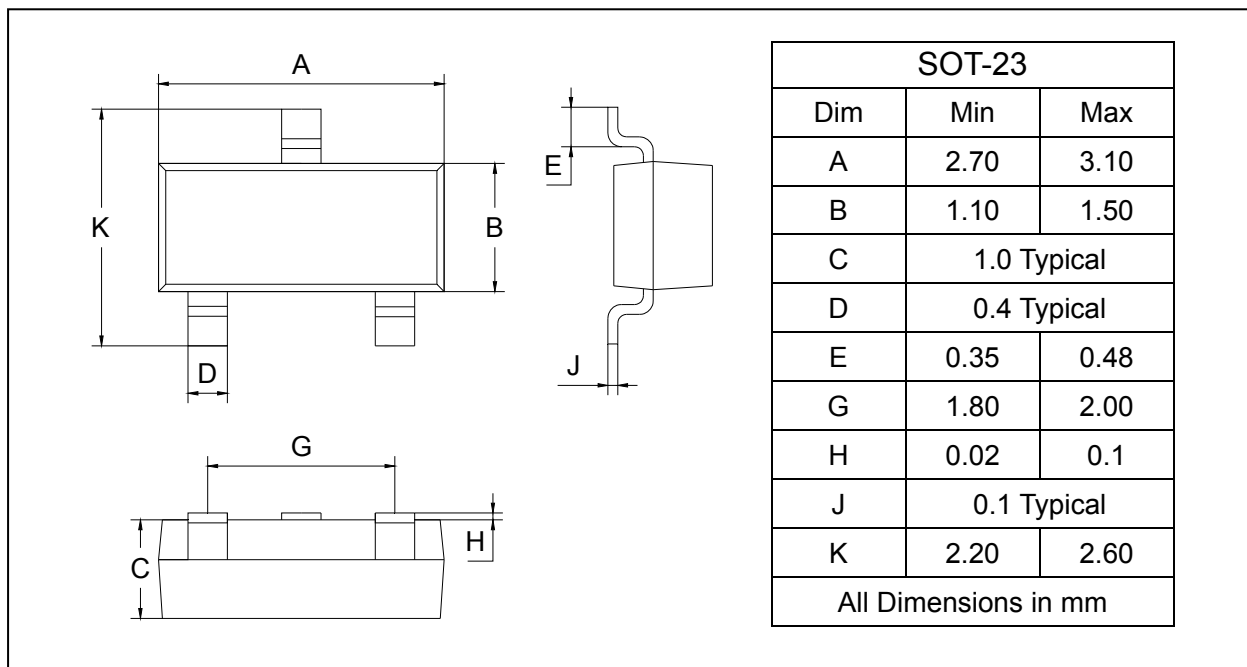
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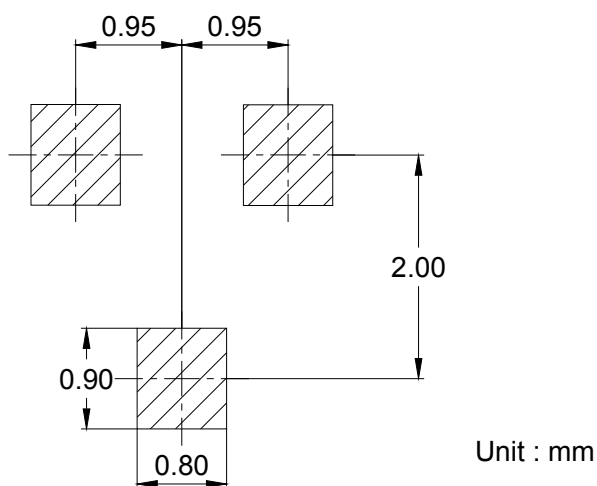
PACKAGE OUTLINE

Plastic surface mounted package

SOT-23



SOLDERING FOOTPRINT



PACKAGE INFORMATION

Device	Package	Shipping
1SS374	SOT-23	3000/Tape&Reel